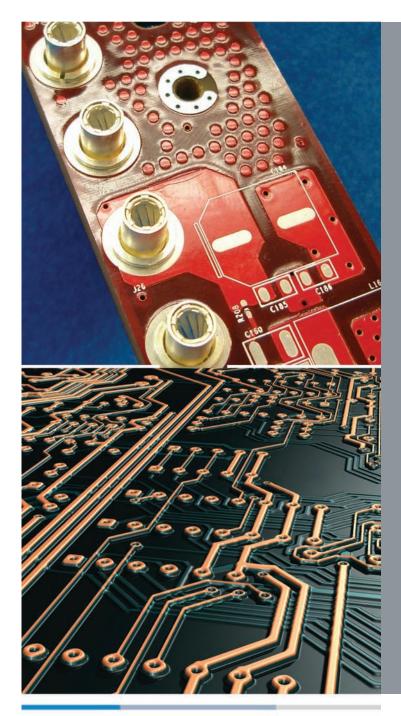
Amphenol[®] Application Note



Radsok[®] RadSert

BACKGROUND

Technological progress leads to more capability in a smaller package with lower cost. In just about everything we see today smaller and lower costs are the objectives being sought to achieve sales and market share. When this objective is applied to a Printed Circuit Board it means that more power needs to be delivered to the board components at the lowest possible cost.

PROBLEM

Adding power to existing PCB designs can be achieved by several methods. The most common method to solve the problem is to increase the thickness of copper layers. This is expensive and traps heat. Another method is to use wires but this causes a "rat's nest" which takes up a lot of space and blocks much of the needed air flow.

AIO SOLUTION

The RADSOK[®] RadSert allows the board designer to bring power to the board from busbars suspended above the board and all of the board components. Pins from the busbar plug into the RADSOK which are installed within the RadSerts. If additional tolerances are needed a SuperTwist RADSOK may be used to allow for greater mating pin – RADSOK misalignment.